

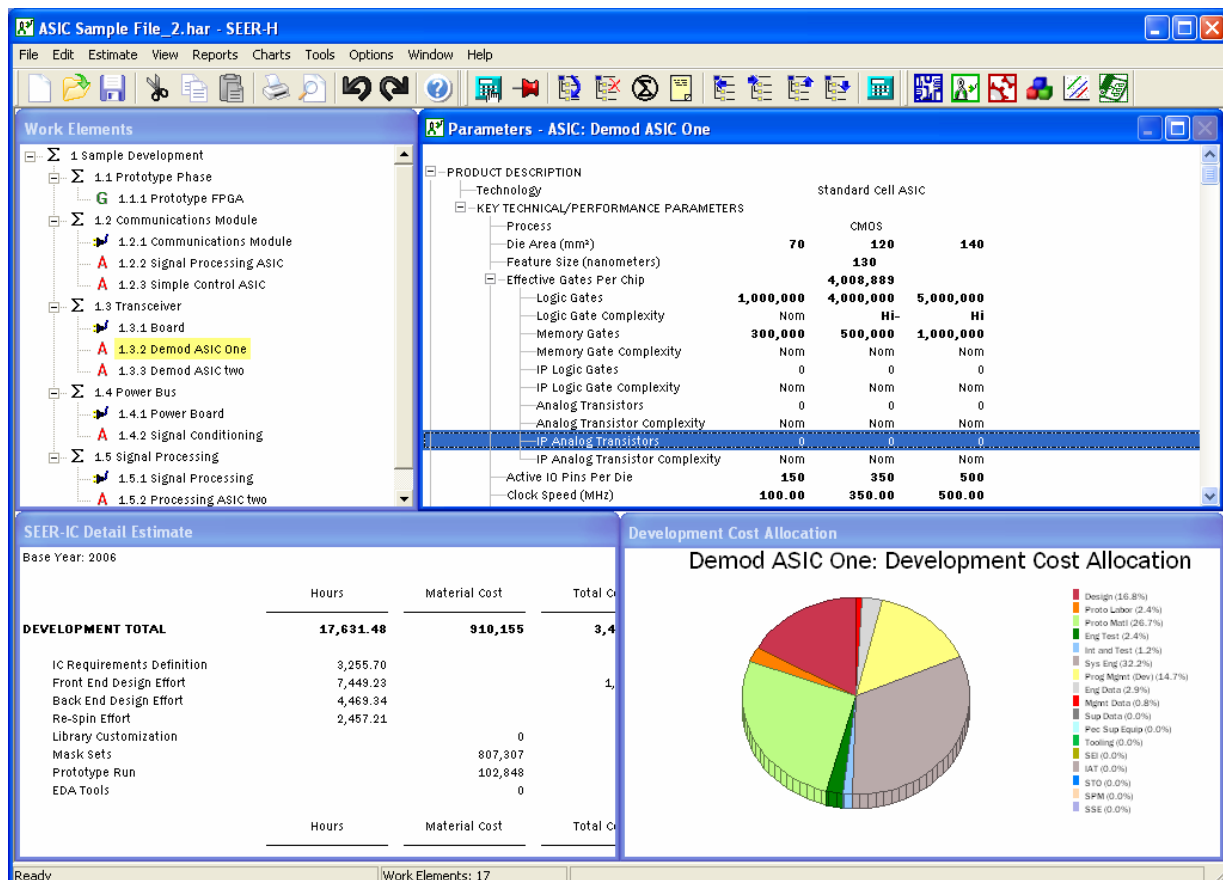
## SEER-IC Plug-in for SEER-H

Dramatic increases in cost and complexity of custom components have made it imperative for Galorath to maintain a dedicated research program into the key cost drivers for this specialist area. Although SEER-H has the functionality to do approximations of IC costs at the PCB and Module level, the SEER-IC plug-in for SEER-H greatly enhances the users' ability to estimate these rapidly evolving technologies.

Many programs are dependent on the architectural approach applied to these key devices for their success. Recent post-mortem research studies conducted by Galorath demonstrate that accurate and reliable estimation of these technologies and their risks are vital to delivering programs on time and on budget whether in ground, airborne or space environments.

SEER-IC will simplify the estimation of development and production costs for custom ICs, ASICS and FPGAs.

Galorath are active in conducting many ASIC research/calibration studies and routinely presents findings to industry leaders. We have expended over two years of extensive research into current industry practices as well as utilizing many man months of consulting time from leading industry experts in integrated circuit technology and commercial practices.



# Typical SEER-IC Parameters

FPGA input parameters	FPGA outputs
<ul style="list-style-type: none"> <li>Active I/O Pins Per Chip</li> <li>Clock Speed or Frequency (MHz)</li> <li>Active Logic Cells</li> <li>New Design %</li> <li>Front End Complexity</li> <li>Back End Complexity</li> <li>Certification Level</li> <li>Developer Capability &amp; Experience</li> <li>Development Tools &amp; Practices</li> <li>Requirements Volatility</li> <li>Prototypes</li> </ul>	<ul style="list-style-type: none"> <li>Architectural Design</li> <li>Detail Design</li> <li>Simulation, Verification, and Implementation</li> <li>Floorplanning, Place, and Route (for advanced applications)</li> <li>Headcount</li> <li>Production total price</li> </ul>
ASIC input parameters	ASIC outputs
<ul style="list-style-type: none"> <li>Process</li> <li>Die Area</li> <li>Feature Size (nanometers)</li> <li>Effective Gates Per Die</li> <li>Logic Gates</li> <li>Logic Gate Complexity</li> <li>Memory Gates</li> <li>Memory Gate Complexity</li> <li>IP Logic Gates</li> <li>IP Logic Gate Complexity</li> <li>Analog Transistors</li> <li>Analog Transistor Complexity</li> <li>IP Analog Transistors</li> <li>IP Analog Transistor Complexity</li> <li>Active I/O Pins Per Die</li> <li>Clock Speed or Frequency (MHz)</li> <li>Wafer Diameter</li> <li>Package Type</li> <li>Radiation Level</li> <li>New Design %</li> <li>Complexity--Front End Design</li> <li>Complexity--Back End Design</li> <li>Certification Level</li> <li>Developer Capability &amp; Experience</li> <li>Development Tools &amp; Practices</li> <li>Requirements Volatility</li> </ul>	<ul style="list-style-type: none"> <li>IC Requirements Definition</li> <li>Front End Design Effort</li> <li>Back End Design Effort</li> <li>Re-Spin Effort</li> <li>Library Customization</li> <li>Mask Sets</li> <li>Prototype Run</li> <li>EDA Tools</li> <li>Unpackaged Die</li> <li>Package</li> <li>Assembly</li> <li>Final Test</li> <li>Qualification Test</li> <li>Minimum Buy Penalty</li> <li>Composite Yield</li> <li>Wafer Yield</li> <li>Qualification Yield</li> <li>Headcount</li> <li>Design Re-Spins</li> <li>Mask Steps</li> <li>Prototype Quantity</li> </ul>